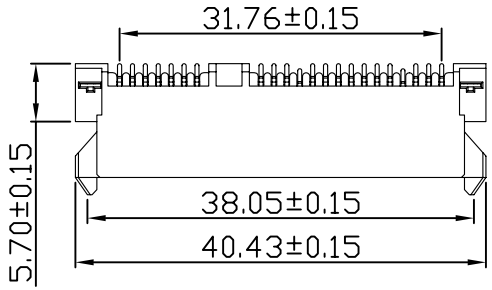
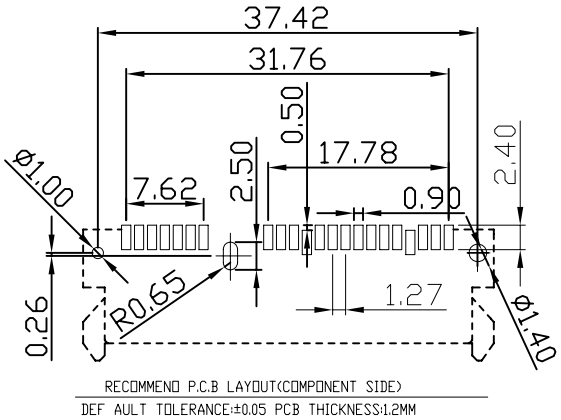
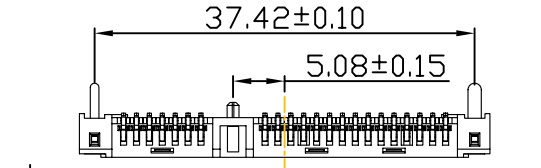


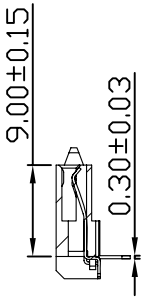




RECOMMEND P.C.B LAYOUT(COMPONENT SIDE)
DEFAULT TOLERANCE:±0.05 PCB THICKNESS:1.2MM

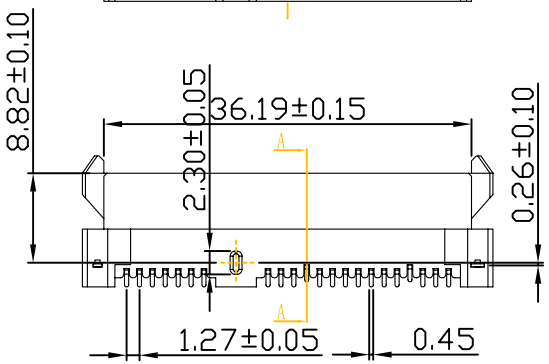


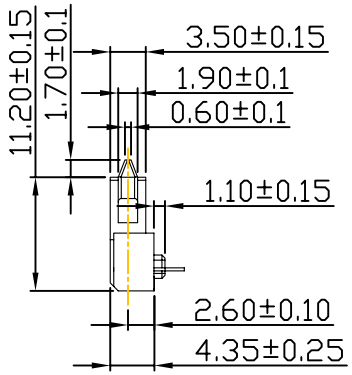

## SPECIFICATIONS

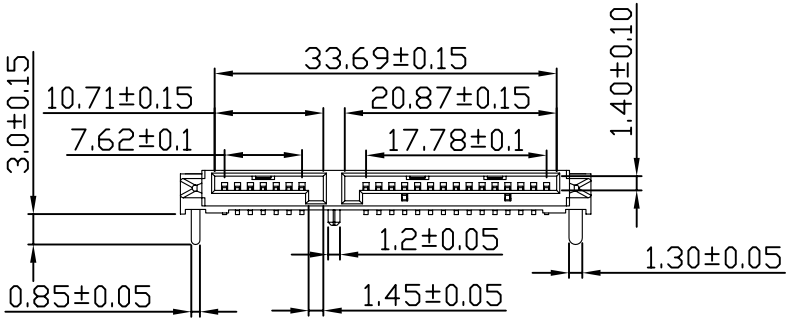
| | |
|---|---|
| ELECTRICAL | |
| RATED CURRENT | :1.0 Amp |
| INSULATION RECICTANCE | :1000 MΩ Min. |
| CONTACT RESISTANCE | :30 mΩ Max. |
| DIELECTRIC WITSTANDING VOLTAGE | :AC 750V FOR 1 MINUTE |
| OPERATING TEMPERATURE | :-40℃～+85℃ |
| MECHANICAL | |
| INSULATOR MATERIAL | :GLASS-FILLED THERMOPLASTIC |
| COLOR | :BLACK (UL94V-0) |
| CONTACT MATERIAL | :BRASS |
| GOLD ON CONTACT AREA, TIN/LEAD ON SOLDERING AREA, ALL OVER NICKEL | |




剖視圖 A-A




| Series | Connector Type | Number of Contacts | Material | Color | Contact Plating | Series |
|---|---|---|---|---|---|---|
| ST C | X | XX | X | XX | XX | X |
| C:C Series | M:SMT Type | (22 Contacts) | N:Nylon-6T<br>C:LCP<br>(Standard:C) | BK:Black<br>BL:Blue<br>GR:Green<br>WH:White<br>YE:Yellow | H1:-5μ″ Min. Gold in contact area/ 100μ″ Min. Tin in solder area/<br>H2:-Fiash. Gold in contact area/ 100μ″ Min. Tin in solder area/<br>H3:-10μ″ Min. Gold in contact area/ 100μ″ Min. Tin in solder area/<br>H4:-15μ″ Min. Gold in contact area/ 100μ″ Min. Tin in solder area/<br>H5:-30μ″ Min. Gold in contact area/ 100μ″ Min. Tin in solder area/ | F:Female |

CHERNG WEEI

**DESCRIPTION**(內容): 1.27mm SATA7+15P Female Reverse SMT type (環保材料)

PART NO: (料號) **STC-M22X-XX-HX-F**

DWG NO(圖號):

DRAWN(製圖): 鄧文廣

CHECKED(確認):

APPROVAL(核准):

GENERAL TOLERANCE: (公差)
.0 ±0.25
.00 ±0.10
.000 ±0.15

SCALE(比例): 1:XX

REV: A/2
UNIT: mm
SIZE: A4
SHEET: 1/1

| REV | DESCRIPTION | DATE |
|---|---|---|
| 1 | | 2007.03.29 |
| 2 | 修改圖面整體尺寸 | 2007.11.05 |
| 3 | 舊料號:CWSATA-M-22CH4-T | 2008.04.09 |
| 4 | | |

FILE NO: CWJ-4E-09

970922